

**NOTICE**

**United Microelectronics Corporation (“UMC”)  
USD 600,000,000 Currency Linked Zero Coupon Convertible Bonds due 2020 (the “Bonds”)  
ISIN: XS1228110000**

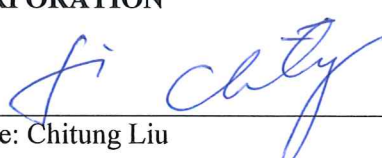
NOTICE IS HEREBY GIVEN that the final redemption of the Bonds was completed on May 18, 2020, the maturity date of the Bonds. The Bonds will be delisted from the SGX-ST.

Pursuant to Article 10 and Condition 8(A) of the Indenture dated as of May 18, 2015 (as amended or supplemented from time to time, the “Indenture”) among UMC and Citicorp International Limited, as trustee (the “Trustee”), relating to the Bonds, and pursuant to the terms of the Bonds, UMC has redeemed all the outstanding Bonds on May 18, 2020, under the following conditions:

The Final Redemption Amount was US\$203,299.62 for each US\$200,000 principal amount of Bonds. The aggregate principal amount of the Outstanding Bonds as of May 18, 2020 was US\$369,400,000.

All capitalized terms used but not defined herein shall have the meaning ascribed to such term in the Indenture.

**UNITED MICROELECTRONICS  
CORPORATION**

  
Name: Chitung Liu

Title: Chief Financial Officer